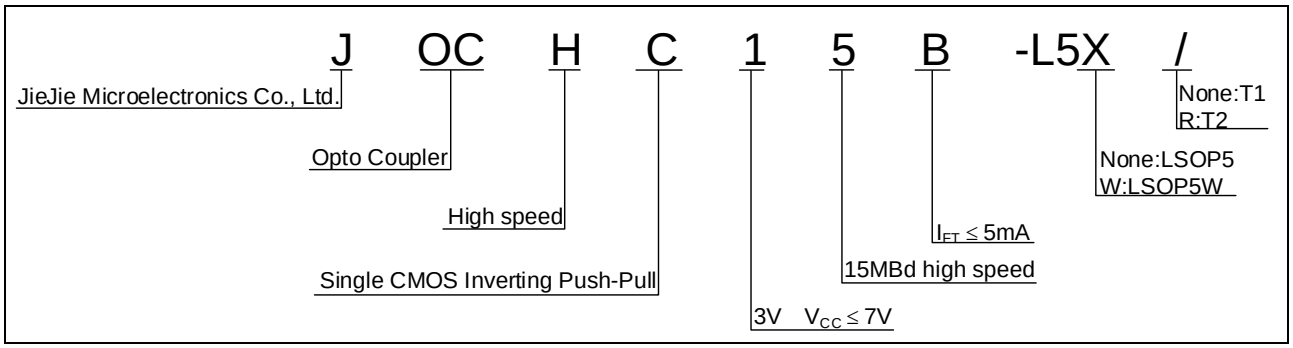
JOCHC15B

	Common Mode Transient Immunity at Logic High	CM_H	I_F=0mA, V_{CM}=1000Vpp, C_L=15pF, V_{CC}=5V	20	-	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM_L	I_F=7mA, V_{CM}=1000Vpp, C_L=15pF, V_{CC}=5V	20	-	-	kV/μs
	Output Rise Time	t_r	I_F=7mA,C_L=15pF	-	10	-	ns
	Output Fall Time	t_f		-	10	-	

Recommended Operating Conditions

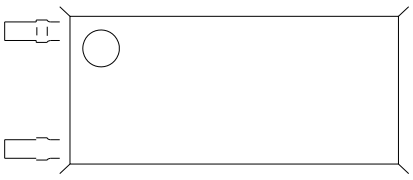
Characteristics	Symbol	Min.	Typ.	Max.	Unit
Operating Temperature	T_a	-40	-	105	
Supply Voltage	V_{CC}	2.7	-	5.5	V
Low Level Input Current	I_{FL}	0	-	250	μA
High Level Input Current	I_{FH}	8	-	Î	

ORDERING INFORMATION



Packing Quantity	
Option	**Quantity**
None/R	3000 Units/Reel

MARKING



Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

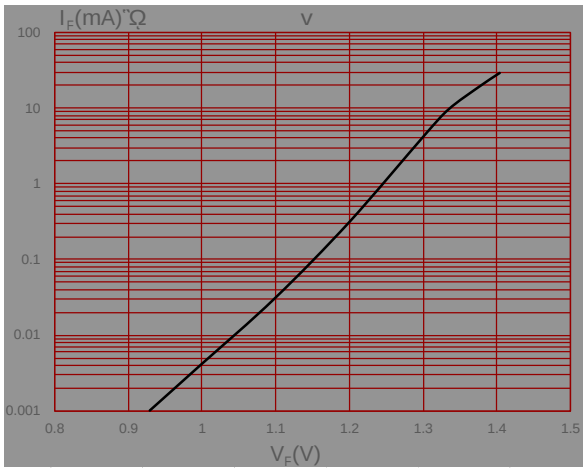


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

FIG.7: Propagation Delay vs. Ambient Temperature

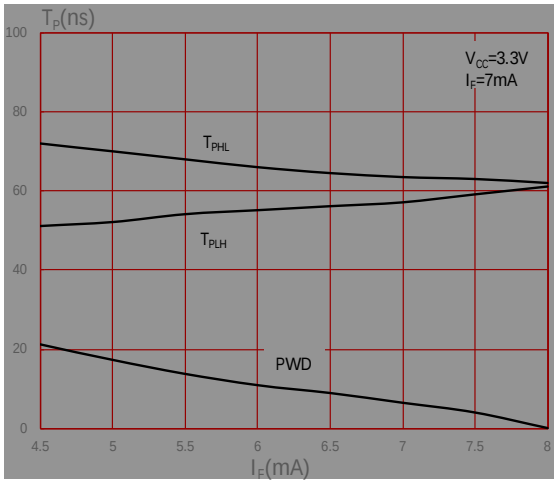
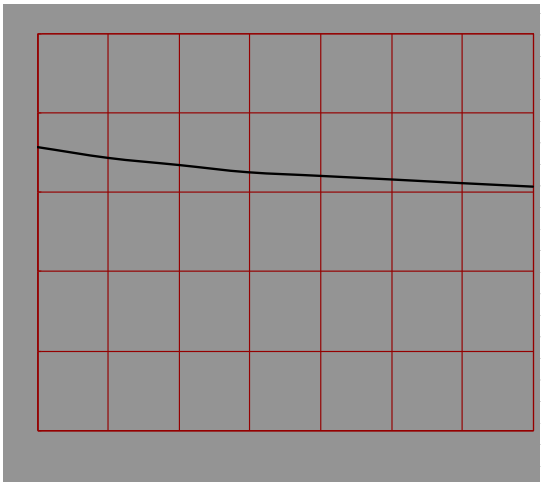
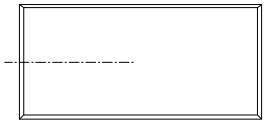


FIG.8: Propagation Delay vs. Ambient Temperature



Package Dimension (Unit: mm)

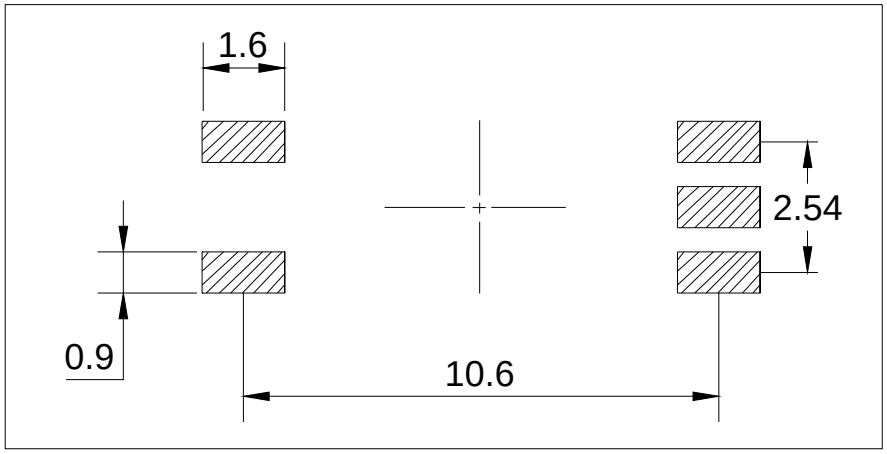
LSOP5



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	7.40		7.80	0.291		0.307
B	3.40		3.80	0.134		0.150
C	0.00		0.20	0.000		0.008
D	1.80		2.20	0.071		0.087
E	8.10		8.70	0.319		0.343
F	0.40		1.00	0.016		0.039
G	9.90		10.50	0.390		0.413
H	0.10		0.30	0.004		0.012
I	1.80		2.40	0.071		0.094
J	0.25		0.55	0.010		0.022
K						

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

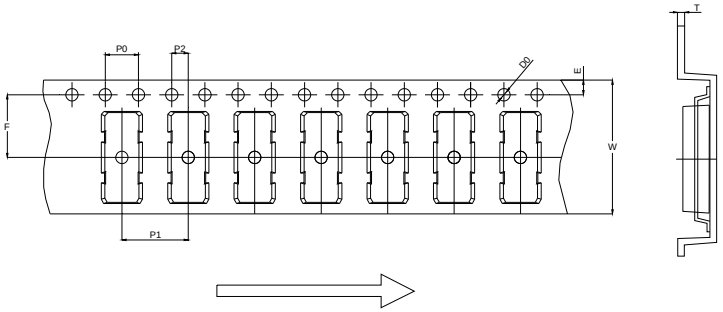
LSOP5



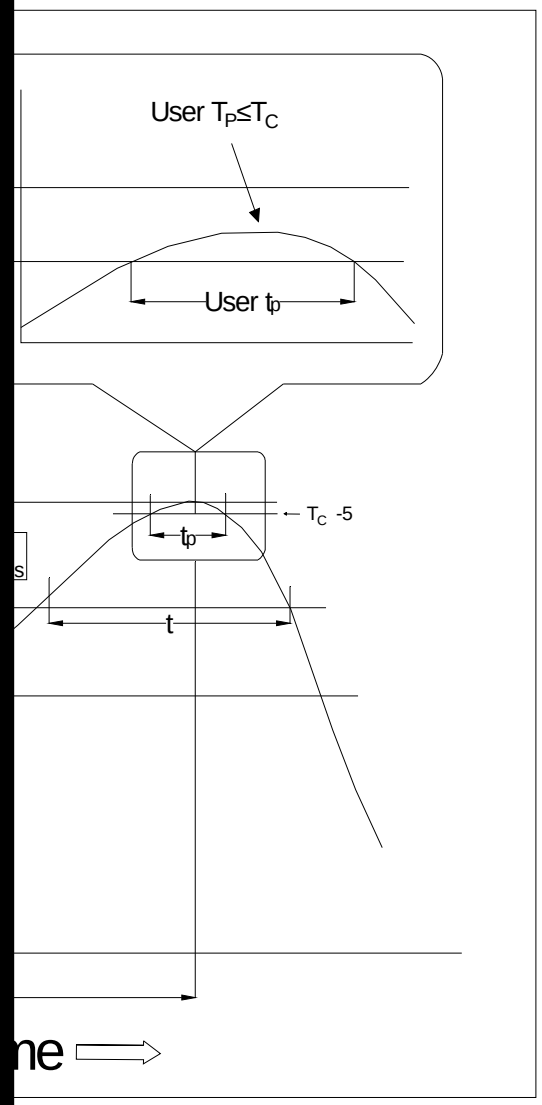
LSOP5W

CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option None/R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0	1.50	1.55	1.60	0.059	0.061	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.80	16.00	16.20	0.622	0.630	0.638



y Profile	Pb-Free Assembly Profile

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1